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Dimensions	
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	5.1mm +/-0.4mm
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

General Information	
Series	KONNEKT Comm COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	650 mg
Chip Size	2220-2
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.2 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	500 MOhms

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